

ABSTRACT

This present application provides a semiconductor packaging method and a semiconductor packaging structure. The semiconductor packaging method includes: forming an encapsulating structure, the encapsulating structure including an encapsulation layer and a chip, the chip provided on a front side thereof with a plurality of bonding pads, the encapsulation layer covering at least side faces of the chip; forming a rewiring layer on the side of the encapsulating structure close to the front side of the chip, the rewiring layer configured for external connection of the bonding pads on the chip; forming a dielectric layer, the dielectric layer covering the rewiring layer, the dielectric layer provided therein with a through hole in which the rewiring layer is exposed; and forming a pin layer on the side of the dielectric layer away from the chip, the pin layer electrically connected to the rewiring layer through the through hole.